TMX JT03

SAW Filter datasheet

3.0 x 3.0 x 1.1 mm, SMD

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Issue: Rev 5, 11 January 2023

TMX JT03

SAW Bandpass Filters | Wireless Communications

Features

Features

- 771 MHz center frequency
- Ceramic package for Surface Mounted Technology
- Typical Passband width: 3 MHz
- Low loss RF Filter and low amplitude ripple
- No matching network required for operation at 50 Ω

Applications

- Wireless applications

3.0 x 3.0 x 1.1 mm

Maximum Ratings

Parameter	Min.	Typ.	Max.	Unit
Storage temperature range (T_{stg})	-40		85	°C
Operating temperature range (T_A)	-40		85	°C
DC voltage (V_{DC})			12	V
RF Power (in Band Width)			15	dBm

Frequency and Electrical Characteristics (Reference temperature @ 25°C)

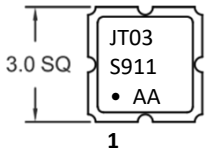
Parameter	Min.	Typ.[1]	Max.	Unit
Center frequency (f_C)		771		MHz
Bandwidth (BW, passband width)	3.00			MHz
Insertion Loss (IL, 769.5 – 772.5 MHz)		2.5	3.0	dB
Passband ripple (769.5 – 772.5 MHz)		0.4	1.0	dB
Absolute Attenuation				
From DC to fc to 471 MHz	40	50		
From 471 to 731 MHz	40	45		
From 731 to 756 MHz	30	40		
From 756 to 758 MHz	10	30		dB
From 784 to 786 MHz	10	30		
From 786 to 811 MHz	25	35		
From 811 to 1071 MHz	40	45		
From 1071 to 2000 MHz	30	40		
VSWR (769.5 – 772.5 MHz)		1.5	2.0	
Source impedance[2] (Single ended)		50		Ω
Load impedance[2] (Single ended)		50		Ω

[1] Typical values are nominal performances at room temperature

[2] No external matching is required

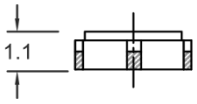
Model Outline, Pin Connection and Marking

TOP VIEW



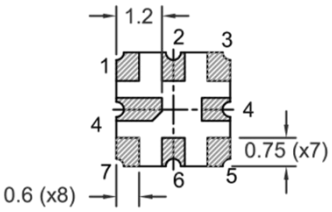
Marking		Note
Line 1	JT03	RakonXpress designation
Line 2	S911	S = Production code 9 = The last digit of year 2019 11 = Week 11 of the year
Line 3	•AA	• = Identify black dot AA = Internal Code (Wafer Batch)

FRONT VIEW

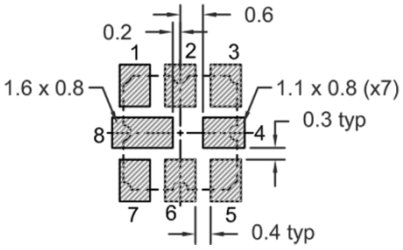


Pin	Connections
2	Input
6	Output
1, 3, 5, 7	To be grounded
4, 8	Case Ground

BOTTOM VIEW



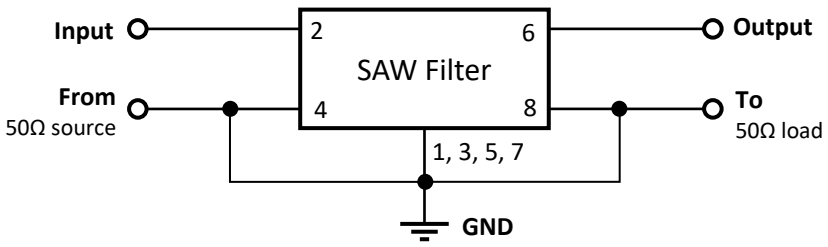
RECOMMENDED PAD LAYOUT
TOP VIEW



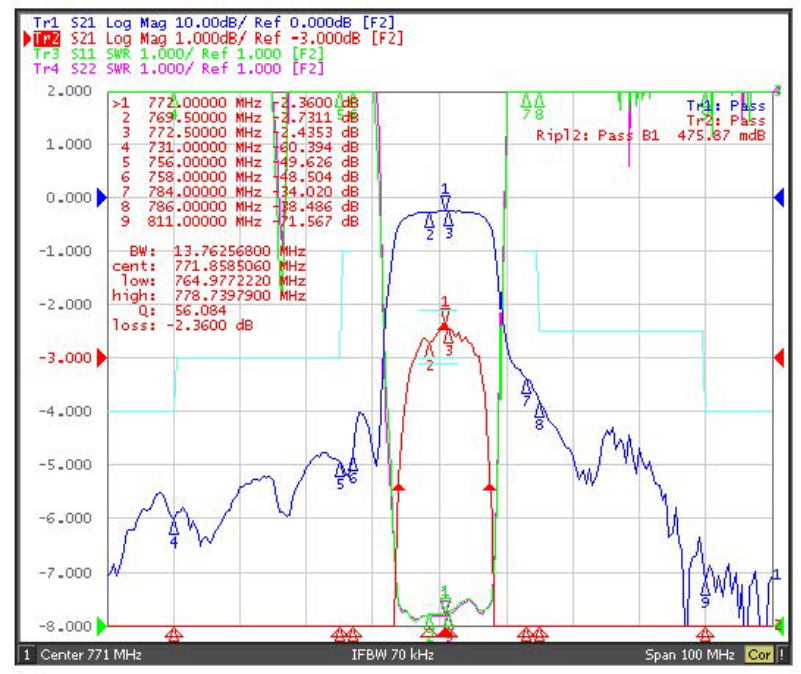
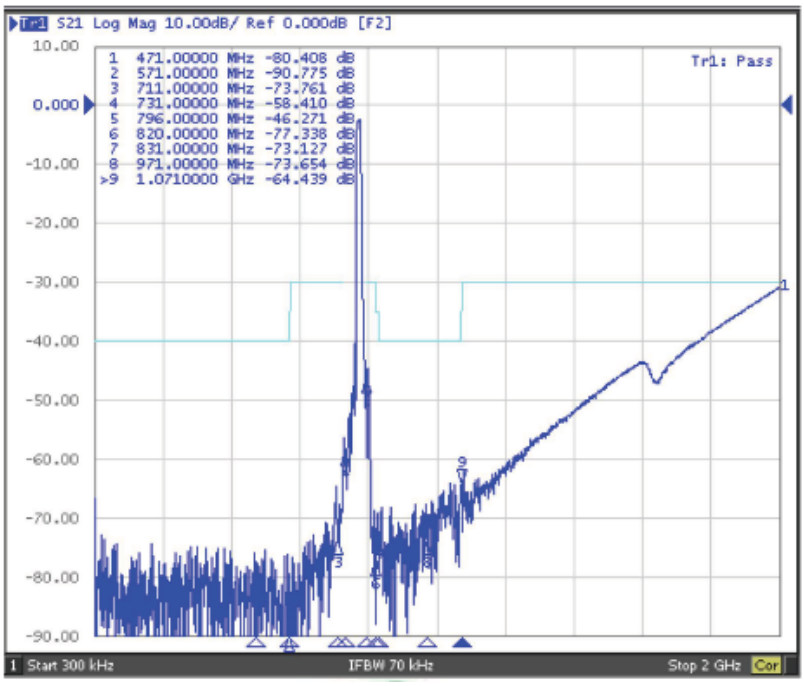
Unit: mm

Test Circuit

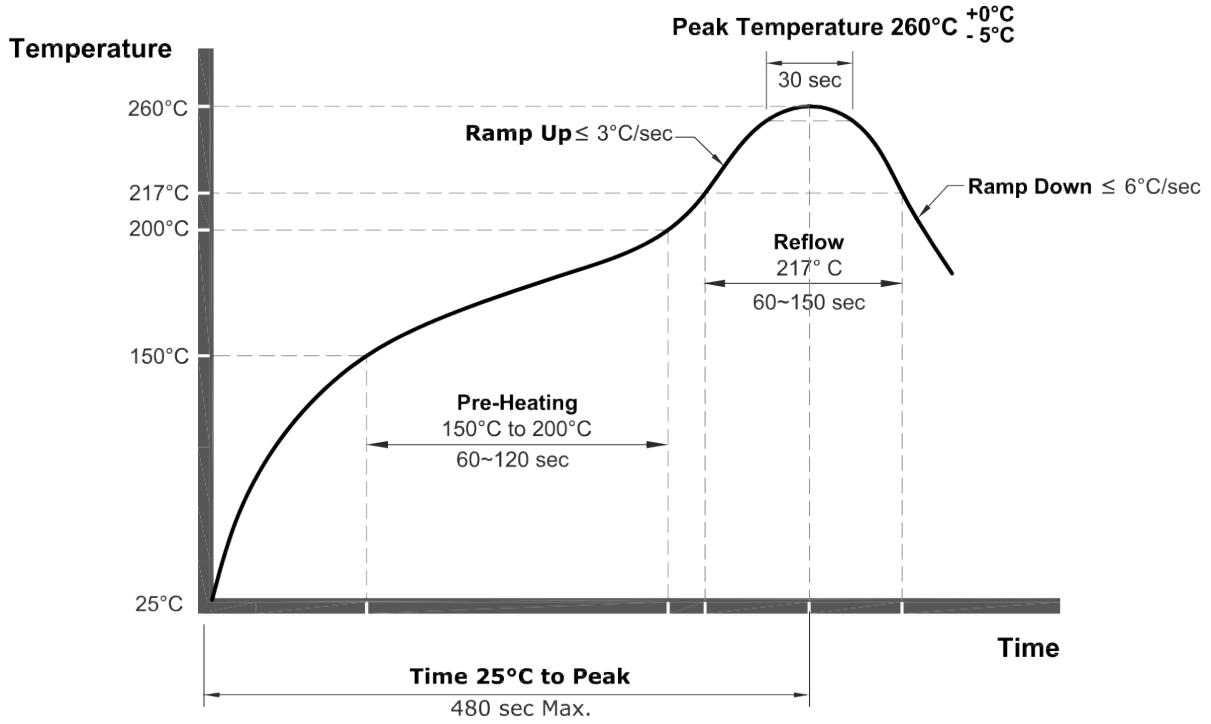
50 Ω / 50 Ω Configuration



Frequency Characteristics

Parameters	Graphs
Typical Frequency Repsonse (S21, S11, S22)	
Typical 21 FAR SIDELOBE	

Recommended Reflow Soldering Profile

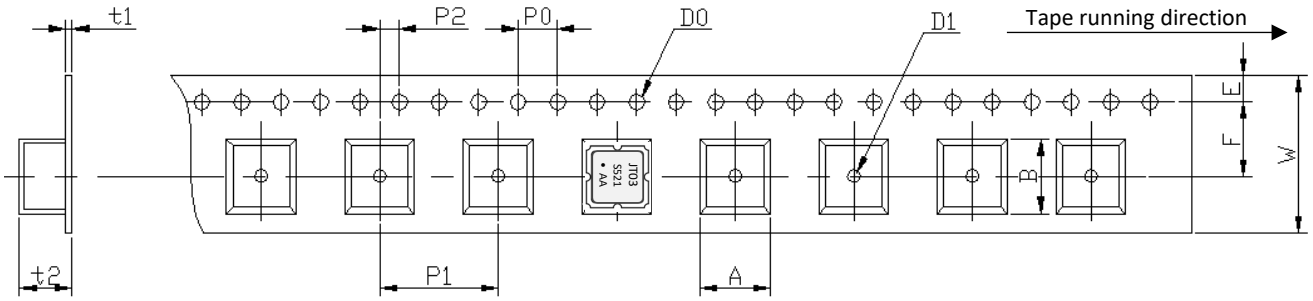


NOTE:

- The components shall remain within the electrical specifications after it soldered on the 1mm thickness PCB board and dipped in the solder at 260 ± 5°C during 10 ± 1 seconds.
- The components shall remain within the electrical specifications after it soldered by electric iron, solder at 350 ± 10 °C during 3~4 seconds. Recovery time: 2 ± 0.5 hour.
- Ultrasonic cleaning may cause deterioration and destruction of the component. Please avoid ultrasonic cleaning.
- Only leads of components may be soldered. Please avoid soldering another part of the component.

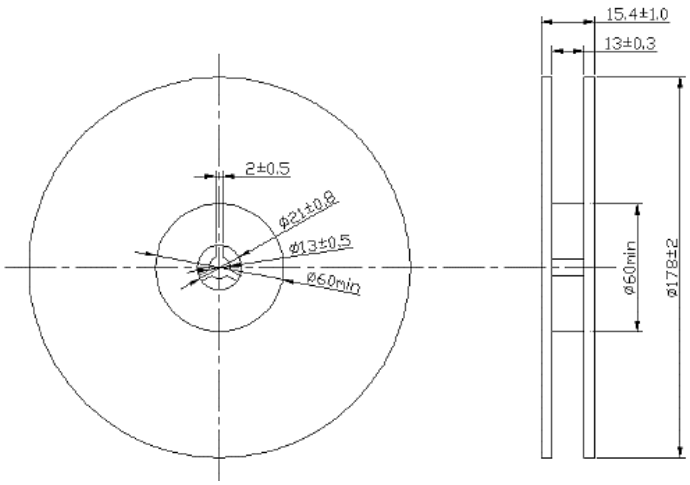
Tape and Reel Specifications

TAPE DETAILS:



Parameter	Code	Dimension	Tolerance
Height of component hole	A	3.3 max	
Width of component hole	B	3.3 max	
Diameter of sprocket hole	D_0	Φ 1.5	± 0.1
Diameter of feed hole	D_1	Φ 1.5	± 0.25
Pitch of sprocket hole	P_0	4.0	± 0.2
Length from hole center to component center	P_1	4.0	± 0.1
Length from Pocket hole center to sprocket hole center	P_2	2.0	± 0.2
Width of carrier tape	W	12.0	± 0.3
Width of adhesive tape	F	5.5	± 0.3
Gap of hold down tape and carrier tape	E	1.75	± 0.1
Thickness of Ebossed tape sheet	t1	0.31 max	
Thickness of Ebossed tape	t2	1.7 max	

REEL DETAILS:



NOTE:

- Unit: mm
- Standard Packing Quantity (SPQ) is 3000 pieces/reel

Reliability Test

Parameter	Test condition / Description
Thermal Shock	The components shall remain within the electrical specifications after being kept at the condition of heat cycle conditions: TA=-40° C ±3° C, TB=85° C ±2° C, t1=t2=30min, switch time ≤3min & cycle time: 100 times, recovery time: 2h±0.5h.
Temperature Storage	High Temperature Storage: The components shall remain within the electrical specifications after being kept at the 85°C ±2°C for 500 hours, recovery time: 2h ±0.5h. Low Temperature Storage: The components shall remain within the electrical specifications after being kept at the -40°C ±3°C for 500 hours, recovery time: 2h ±0.5h.
Humidity test	The components shall remain within the electrical specifications after being kept at the condition of ambient temperature 60°C ±2°C, and 90~95% RH for 500 hours.
Drop test	The components shall remain within the electrical specifications after random free drops 10 times from height of 1.0 meter onto concrete floor, and the specimens shall meet the electrical specifications.
Vibration Fatigue	The components shall remain within the electrical specifications after loaded vibration at 10~55Hz, amplitude 1.5mm, X, Y, Z, direction, during 2 hours.
Mechanical Shock	The components shall remain within the electrical specifications after 1000 shocks, acceleration 392 m/s^2 , duration 6ms.
Note	As a result of the particularity of inner structure of SAW products, the components can easily be breakdown by electrostatic shock; so it's mandatory to pay attention to ESD protect during the tests.